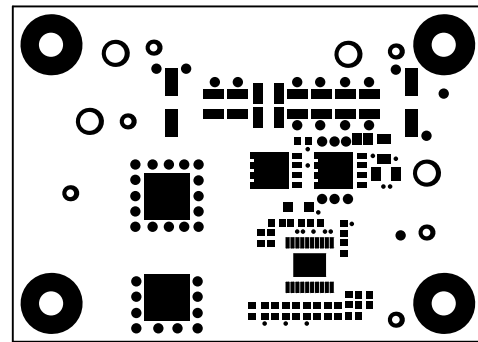
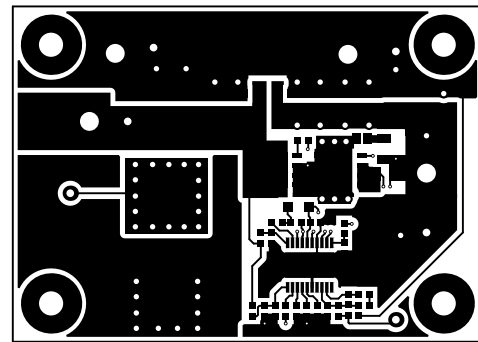


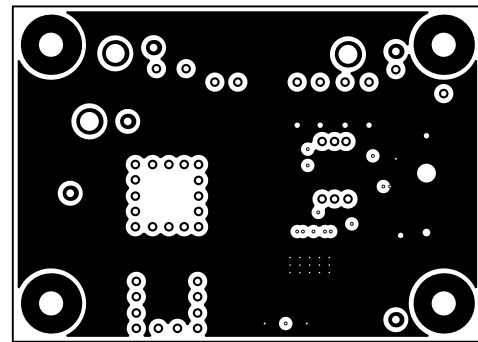
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP20904		
PLOT NAME = Top Overlay	GENERATED : 7/2/2017	5:14:57 PM	TEXAS INSTRUMENTS



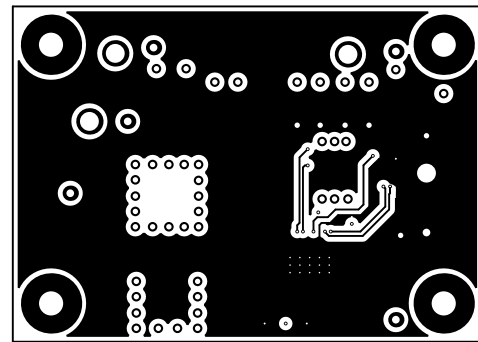
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP20904		
PLOT NAME = Top Solder Mask	GENERATED : 7/2/2017 5:14:57 PM	TEXAS INSTRUMENTS	



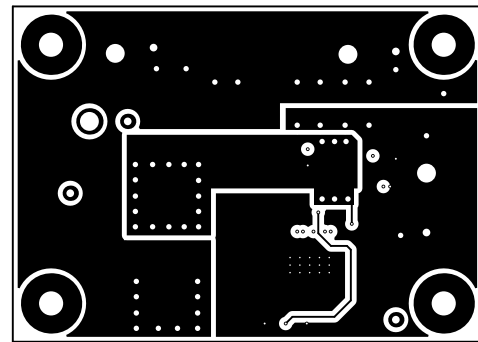
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP20904		
PLOT NAME = Top Layer	GENERATED : 7/2/2017	5:14:58 PM	TEXAS INSTRUMENTS



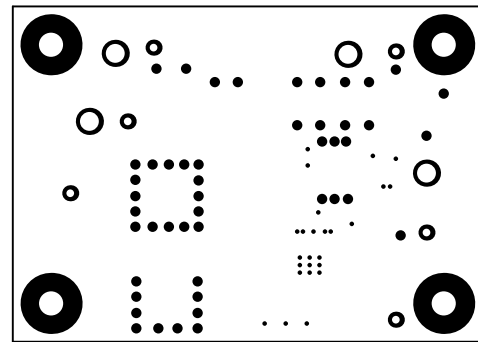
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP20904		
PLOT NAME = Signal Layer 1	GENERATED : 7/2/2017 5:14:59 PM	TEXAS INSTRUMENTS	



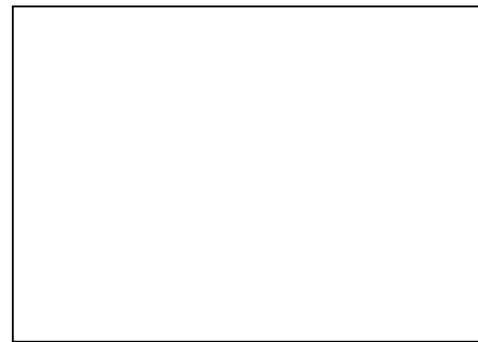
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP20904		
PLOT NAME = Signal Layer 2	GENERATED : 7/2/2017	5:15:00 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP20904		
PLOT NAME = Bottom Layer	GENERATED : 7/2/2017 5:15:01 PM	TEXAS INSTRUMENTS	

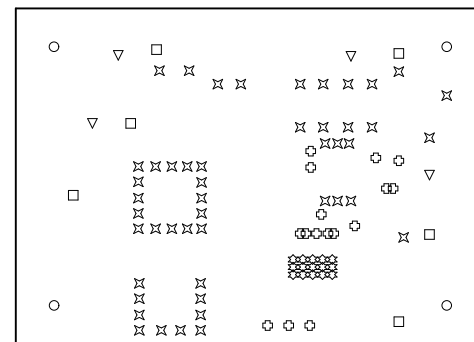


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP20904		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/2/2017 5:15:02 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP20904		
PLOT NAME = Bottom Overlay	GENERATED : 7/2/2017 5:15:04 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊛	15	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	16	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	48	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
□	6	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	93 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP20904		
PLOT NAME = Drill Drawing	GENERATED : 7/2/2017	5:15:05 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20904	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP20904		
PLOT NAME = Board Dimensions	GENERATED : 7/2/2017	5:15:06 PM	TEXAS INSTRUMENTS

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